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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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One-part Epoxy, General Purpose Adhesive, High T_g

Description

9310 a is general purpose, one-part epoxy adhesive. It is smooth, thixotropic, self-leveling, and bonds well to a wide variety of substances. It has an unlimited working life at room temperature and does not require frozen storage.

This product is designed for use in electronic assembly operations. It does not require mixing and can be readily used in manual, pneumatic and robotic dispensing processes.

9310 has been formulated to have a high T_g. For a low T_g, use 9300.

Features and Benefits

- Minimum cure temperature of 100 °C [212 °F]
- Unlimited working life
- Shelf life: 2 years at room temperature
- Provides strong electrical insulation
- T_g of 113 °C [235 °F]
- Strong resistance to humidity, salt water, acids, bases, and aliphatic hydrocarbons

Usage Parameters

Properties	Value
Working life @22 °C [72 °F]	Unlimited
Shelf life @22 °C [72 °F]	2 y
Full cure @22 °C [72 °F]	Heat cure only
Full cure @100 °C [212 °F]	30 min
Full cure @120 °C [248 °F]	10 min

Temperature Ranges

Properties	Value
Constant service temperature	-55 to 140 °C [-67 to 284 °F]
Storage temperature	-10 to 27 °C [14 to 81 °F]

Cured Properties

Physical Properties	Method	Value ^{a)}
Color	Visual	Amber
Density @25 °C [77 °F]	ASTM D 1475	1.13 g/mL
Hardness	Shore D Durometer	84D
Tensile strength	ASTM D 638	9.4 N/mm ² [1 360 lb/in ²]
Compressive strength	ASTM D 695	103 N/mm ² [15 000 lb/in ²]
Lap shear strength (stainless steel)	ASTM D 1002	8.5 N/mm ² [1 200 lb/in ²]
Lap shear strength (aluminum)	ASTM D 1002	6.2 N/mm ² [890 lb/in ²]
Lap shear strength (copper)	ASTM D 1002	7.8 N/mm ² [1 100 lb/in ²]
Lap shear strength (brass)	ASTM D 1002	6.7 N/mm ² [980 lb/in ²]
Lap shear strength (polycarbonate)	ASTM D 1002	0.9 N/mm ² [136 lb/in ²]
Electrical Properties	Method	Value
Breakdown voltage @4.9 mm	ASTM D 149	41 600 V [41.6 kV]
Dielectric strength @4.9 mm	ASTM D 149	220 V/mil [8.6 kV/mm]
Breakdown voltage @3.175 mm [1/8"]	Reference fit ^{b)}	34 000 V [34 kV]
Dielectric strength @3.175 mm [1/8"]	Reference fit ^{b)}	270 V/mil [10 kV/mm]
Volume resistivity	ASTM D 257	9.3 x 10 ¹² Ω·cm
Volume conductivity	ASTM D 257	1.1 x 10 ⁻¹³ S/cm

Note: Specifications are for epoxy samples cured at 100 °C for 30 min and conditioned at ambient temperature and humidity.

a) N/mm² = mPa; lb/in² = psi

b) To allow comparison between products, the dielectric strength was recalculated with the Tautscher equation fitted to 5 experimental values and extrapolated to a standard thickness of 1/8" (3.175 mm).

Cured Properties

Thermal Properties	Method	Value
Glass transition temperature (T _g)	ASTM E 831	113 °C [235 °F]
CTE ^{a)} prior T _g after T _g	ASTM E 831 ASTM E 831	56 ppm/°C [133 ppm/°F] 185 ppm/°C [365 ppm/°F]
Thermal conductivity @25 °C [77 °F] @50 °C [122 °F] @100 °C [212 °F]	ASTM E 1461 92 ASTM E 1461 92 ASTM E 1461 92	0.24 W/(m·K) 0.26 W/(m·K) 0.29 W/(m·K)
Thermal diffusivity @25 °C [77 °F]	ASTM E 1461 92	0.2 mm ² /s
Specific heat capacity @25 °C [77 °F]	ASTM E 1461 92	1.4 J/(g·K)

Note: Specifications are for epoxy samples cured at 100 °C for 30 min and conditioned at ambient temperature and humidity.

a) Coefficient of Thermal Expansion (CTE) units are in ppm/°C = in/in/°C × 10⁻⁶ = unit/unit/°C × 10⁻⁶

Uncured Properties

Physical Properties	Method	Value
Color	Visual	Amber
Viscosity @25 °C [77 °F]	IPC TM-650 Method 2.4.34.4	86 500 cP [86.5 Pa·s] ^{a)}
Density	ASTM D 1475	1.15 g/mL

a) Brookfield viscometer at 3 rpm with spindle RV S92

Compatibility

Adhesion—9310 epoxy adheres to most plastics and metals used to house printed circuit assemblies; however, it is not compatible with contaminants like water, oil, or greasy flux residues that may affect adhesion. If contamination is present, first clean the surface to be coated with MG Chemicals 824 Isopropyl Alcohol.

For substrates with weak adhesion strength, surface preparation (such as sanding, or pre-coating with a suitable primer) may improve adhesion.

Chemical—The cured epoxy adhesive is inert under normal conditions. It can tolerate short-term exposure to fuels or similar non-polar organic solvents, but it may not be suitable for prolonged exposure. Avoid using with strong acids, strong bases, or strong oxidizers.

Storage

Store between -10 and 27 °C [14 and 81 °F] in a dry area, away from sunlight. Some of the components are sensitive to air. To maximize shelf life, always recap product firmly when not in use.

Health and Safety

Please see the 9310 Safety Data Sheet (SDS) for further details on transportation, storage, handling, safety guidelines, and regulatory compliance.

Application Instructions

For best results, follow the procedure below. This product does not require mixing prior to use, and can be applied with a spatula, trowel, or automated dispensing machine.

Syringe or cartridge:

1. For 10 mL size, twist and remove the cap from the syringe. Do not discard the cap.
2. For the 300 mL size, cut the end of the cartridge tip.
 - a. Screw the tip on the cartridge.
 - b. Insert the cartridge in a caulking gun.
3. Dispense the adhesive evenly to both surfaces.
4. To stop the flow, pull back on the plunger.
5. Clean nozzle to prevent contamination and material buildup.
6. Replace the cap on the cartridge or syringe.

Cure Instructions

Room temperature cure:

Do NOT cure at room temperature. This product will only cure at elevated temperatures.

Heat cure:

- Put in oven at 100 °C [212 °F] for 30 min.
—OR—
- Put in oven at 120 °C [248 °F] for 10 min.

Dispensing Accessories

9310-300ML cartridges are compatible with caulking guns that are readily available for purchase at local hardware stores.

Packaging and Supporting Products

Cat. No.	Packaging	Net Volume	Packaged Weight
9310-10ML	Syringe	10 mL [0.33 fl oz]	0.04 kg [0.09 lb]
9310-300ML	Cartridge	300 mL [10.1 fl oz]	0.47 kg [1.03 lb]

Technical Support

Please contact us regarding any questions, suggestions for improvements, or problems with this product. Application notes, instructions and FAQs are located at www.mgchemicals.com.

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